

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A plasma processing device comprising:
an inject plate including a first hole with a first diameter;
an upper electrode including a second hole with a recessed area having a second diameter larger than the first diameter; and
a hybrid ball-lock device configured to removably securing secure the inject plate to the upper electrode by expanding into the recessed area.

Claim 2 (Original): The plasma processing device of claim 1, wherein the hybrid ball-lock device comprises an actuating hybrid ball-lock device.

Claim 3 (Original): The plasma processing device of claim 1, wherein the hybrid ball-lock device comprises an actuating hybrid spring-plunger device.

Claim 4 (Original): The plasma processing device of claim 1 wherein the hybrid ball-lock device comprises a ceramic head.

Claim 5 (Original): The plasma processing device of claim 1 wherein the hybrid ball-lock device comprises a silicon head.

Claim 6 (Original): The plasma processing device of claim 1 wherein the hybrid ball-lock device comprises a quartz head.

Claim 7 (Original): The plasma processing device of claim 1 wherein the hybrid ball-lock devices comprises an anodized aluminum head.

Claim 8 (Original): The plasma processing device of claim 1 wherein the hybrid ball-lock device comprises a metallic head.

Claim 9 (Original): The plasma processing device of claim 6 wherein the head is coated with a ceramic material.

Claim 10 (Original): The plasma processing device of claim 1, wherein the hybrid ball-lock device comprises a CRES fastener housing.

Claim 11 (Original): The plasma processing device of claim 1 wherein the hybrid ball-lock device or threaded shaft is removably connected to a release button.

Claim 12 (Original): The plasma processing device of claim 1, wherein the hybrid ball-lock device comprises at least one retaining ball.

Claim 13 (Withdrawn): A method of using a hybrid ball-lock device in a plasma processing device comprising the steps of:

communicatively locating a first surface of a first plasma processing device component adjacent a second surface of a second plasma processing device component;
inserting a hybrid ball-lock device into a recess located in at least one of the first and second plasma processing device components;

wherein the hybrid ball-lock device is inserted until a retaining ball is in communication with a retaining ball receiving recess contained within at least one of the first and second plasma processing device components.

Claim 14 (Withdrawn): The method of using a hybrid ball-lock device as claimed in claim 13, wherein the ball-lock device comprises a hybrid spring plunger type ball-lock device.

Claim 15 (Withdrawn): The method of using a hybrid ball-lock device as claimed in claim 13, wherein the hybrid ball-lock device comprises an actuating type hybrid ball-lock device.

Claim 16 (Withdrawn): The method of using a hybrid ball-lock device as claimed in claim 13, wherein at least a second hybrid ball-lock device is used.

Claim 17 (Withdrawn): The method of using a hybrid ball lock device as claimed in claim 13, wherein the first plasma processing device component comprises an upper electrode including an upper electrode portion and a lower electrode portion, and the head of the hybrid ball-lock device is in contact with an inject plate.

Claim 18 (Withdrawn): The method of using a hybrid ball-lock device as claimed in claim 17, further comprising interposing a baffle plate and a lower electrode between the upper electrode portion and the inject plate, wherein the baffle plate and the lower electrode portion includes holes therein for receiving the hybrid ball-lock device.

Claim 19 (New): The plasma processing device claim 1, further comprising a process chamber in which the inject plate is removably secured by the hybrid ball-lock device, and the inject plate is configured to accept insertion to the ball-lock device from inside the process chamber.

Claim 20 (New): The plasma processing device of claim 19, wherein the second hole is a blind hole.

Claim 21 (New): The plasma processing device of claim 19, wherein the hybrid ball-lock device comprises a spring with an axis oriented perpendicular to an axis of the second hole and configured to push a ball into the recessed area.